

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Inductors

3D transponder coils Size $11.5 \times 12.5 \times 3.6$ (mm)

Series/Type: B82453C*A

Date: June 2017

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Transponder coils

B82453C*A

Size 11.5 x 12.5 x 3.6 (mm)

<u>SMD</u>

Construction

- Special core geometry
- Ferrite core with stability in temperature
- Laser-welded
- High thermal class wire
- Flame-retardant molding

Features

- Long receiving distance at 125 kHz
- Qualified to AEC-Q200
- High sensitivity in all orientations (X/Y/Z)
- Suitable for pick and place and AOI (Automatic Optical Inspection)
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020E
- RoHS-compatible

Applications

Passive entry, passive start (PEPS): wake-up and immobilzer LF antenna coil

Terminals

- Base material CuSn4
- Layer composition Sn (lead-free)
- Lead-free tinned

Delivery mode and packing unit

- 24-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 900 pcs./reel





Transponder coils

B82453C*A

- P6

- P5

IND1387-Q

X-axis

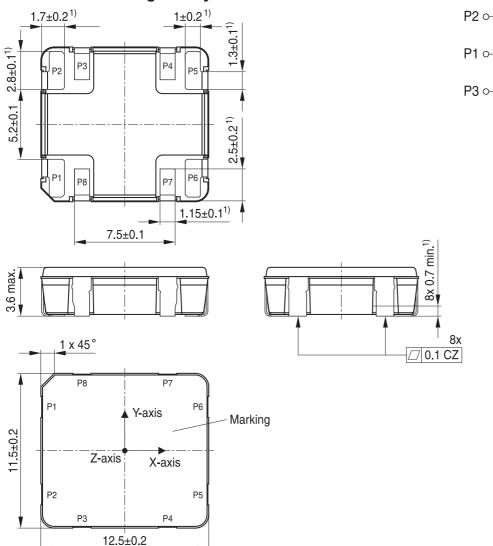
Y-axis

Z-axis

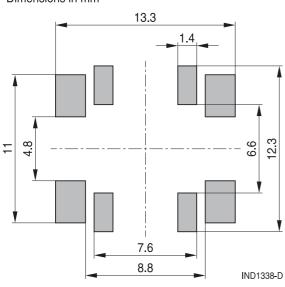
Size 11.5 x 12.5 x 3.6 (mm)

SMD

Dimensional drawing and layout recommendation



1) Soldering area Dimensions in mm



IND1334-9-E

Dimensions in mm



Transponder coils B82453C*A

Size 11.5 x 12.5 x 3.6 (mm)

SMD

Marking

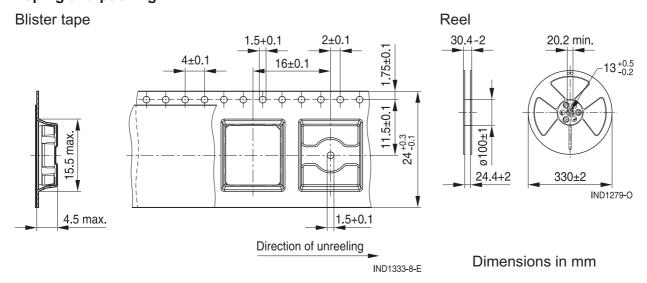


① Cxxxx A000

4 39 2 ② ③ ④ 33 (5)

1	Last 9 d	characte	9 characters/digits						
2	Year (10 years cycle): 2011 -> 1 2012 -> 2 2020 -> 0								1 digit
3	Calendar week: 01 53								2 digits
4	Day of t	the weel	1 digit						
	Day	Sun	Mon	Tue	Wed	Thu	Fri	Sat	
	Code	0	1	2	3	4	5	6	
		•	•	•	•		•	·	
5	Last 2 digits of the Lot No. (eg. "107865633" -> "33")								2 digits

Taping and packing





Transponder coils B82453C*A

Size 11.5 x 12.5 x 3.6 (mm)

SMD

Technical data and measuring conditions

Rated inductance L _R	Measured with Agilent 4294A at frequency f _L , RMS voltage 100 mV, +25 °C				
L tolerance	±3%				
Q factor Q _{typ}	Measured with Agilent 4294A at frequency f _Q , RMS voltage 100 mV, +25 °C				
Sensitivity S _{typ}	Measured with Helmholtz coil test setup at f _S				
Resonance frequency f _{res,min}	Measured with Agilent 4294A, +25 °C				
DC resistance R _{DC,max}	Measured with Burster Resistomat 2328, +25 °C				
f_L, f_Q, f_S	125 kHz				
Solderability	Sn96.5Ag3.8Cu0.7: $+(245 \pm 5)$ °C, 5 s Wetting of soldering area \geq 95% (based on JEDEC J-STD 002D)				
Resistance to soldering heat	245 °C, 30 s (as referenced in JEDEC J-STD 020E)				
Climatic category	40/85/56 (to IEC 60068-1)				
Storage conditions	Mounted: -40 °C +85 °C Packaged: -20 °C +40 °C, ≤ 75% RH				
Weight	Approx. 1.7 g				



Transponder coils B82453C*A

Size 11.5 x 12.5 x 3.6 (mm)

SMD

Characteristics and ordering codes

Axis	L _R	Q _{typ} -10%/ +15%	S _{typ}	f _{res,min}	R _{DC,max}	Ordering code
		-10%/+15%	mV			
	mH		μT	kHz	Ω	
X	4.75	23.5	60	600	80	
Υ	4.75	23.5	57	600	80	B82453C0300A000
Z	5.85	19.0	45	400	165	
X	4.75	23.5	60	600	80	
Υ	4.75	24.5	57	600	80	B82453C0203A000
Z	7.20	19.5	50	400	165	
X	7.20	23.5	80	400	95	
Υ	7.20	24.5	75	420	100	B82453C0275A000
Z	7.20	19.5	50	400	165	
X	6.30	23.5	75	440	90	
Υ	6.30	24.5	70	460	90	B82453C0285A000
Z	9.00	19.5	63	360	190	
X	6.30	23.5	75	440	90	
Υ	6.30	24.5	70	460	90	B82453C0301A000
Z	11.00	19.5	73	330	220	
X	6.75	23.5	77	430	92	
Υ	6.75	24.5	73	450	95	B82453C0270A000
Z	13.20	19.5	83	300	250	

Characteristics and ordering codes for other L values available on request.



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

 Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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